L Number	Hits	Search Text	DB	Time stamp
1	2077	(flexible same (board or substrate)) and dies	USPAT;	2004/08/19 10:29
'	20.7	(noxible ballie (boal a or babbliate)) alla ales	EPO; JPO;	2004/06/19 10.29
			DERWENT:	
			USOCR	
2	56	(flexible same (board or substrate)) and dies and	USPAT;	2004/08/19 09:52
-	"	overmold\$3	EPO; JPO;	2004/00/19 09.52
		- overmonage	DERWENT;	
			USOCR	
3	15929	BGA or (ball adj grid adj array)	USPAT:	2004/08/19 10:03
	10020	box or (ball adj grid adj array)	EPO; JPO;	2004/00/19 10.03
			DERWENT;	
5	40	((flexible same (board or substrate)) and dies and	USOCR USPAT;	0004/00/40 40:40
"	70	overmold\$3) and (BGA or (ball adj grid adj array))	EPO; JPO;	2004/08/19 10:18
		overmoldys) and (box or (ball adj grid adj array))		
			DERWENT;	
6	3	/"4000040"   "4004047"   "5400054"\ DN	USOCR	0004/00/40 40 07
6	_ :	("4980219"   "4981817"   "5182851").PN.	USPAT	2004/08/19 10:05
7	4	("3766439"   "5117282"   "5313416"   "5335145").PN.	USPAT	2004/08/19 10:06
8	33	5448511.URPN.	USPAT	2004/08/19 10:06
9	17	("3341742"   "3454911"   "4426689"   "4781601"	USPAT	2004/08/19 10:08
		"5179501"   "5220488"   "5252857"   "5345205"		
		"5382829"   "5448511"   "5451774"   "5452182"		
		"5519578"   "5544015"   "5634194"   "5747743"		
		"5767824").PN.		
10	13	("3152288"   "3248779"   "3766439"   "3873889"	USPAT	2004/08/19 10:09
		"3971127"   "4490721"   "4495546"   "4591814"		
		"4716259"   "4792879"   "4816836"   "4967201"		
		"5005019").PN.		
11	19	5345205.URPN.	USPAT	2004/08/19 10:10
12	7	("5117282"   "5170328"   "5345205"   "5776797"	USPAT	2004/08/19 10:11
		"6014316"   "6172418"   "6208521"		
40	00	"2001/0015487").PN.		
13	20	("3242384"   "3873889"   "4991290"   "5008496"	USPAT	2004/08/19 10:12
		"5220488"   "5224023"   "5252857"   "5265322"		
		"5345205"   "5386341"   "5448511"   "5519578"		İ
		"5565705"   "5646446"   "5717556"   "5789815"		
44		"5805422"   "5926369"   "5956234"   "5963427").PN.		
14 15	4	("4066851"   "4402135"   "4710419"   "4772496").PN.	USPAT	2004/08/19 10:14
16	29	5008496.URPN.	USPAT	2004/08/19 10:14
16	169	dies and overmold\$3	USPAT;	2004/08/19 10:19
			EPO; JPO;	
			DERWENT;	
17	4.0	dies and supressides and many	USOCR	
''	46	dies and overmold\$3 and rows	USPAT;	2004/08/19 10:19
	[		EPO; JPO;	
			DERWENT;	1
40		(diamond accompatation and a control of the control	USOCR	
18	45	(dies and overmold\$3 and rows) and (board or	USPAT;	2004/08/19 10:19
		substrate)	EPO; JPO;	
		·	DERWENT;	
40		// !!	USOCR	
19	27	((dies and overmold\$3 and rows) and (board or	USPAT;	2004/08/19 10:23
		substrate)) and (BGA or (ball adj grid adj array))	EPO; JPO;	
]			DERWENT;	
		057/707 700 1 1/7 11 1	USOCR	
20	27	257/787-790.ccls. and (flexible and overmold\$3)	USPAT;	2004/08/19 10:26
			EPO; JPO;	
]			DERWENT;	
	_	(1150070471141100757467147147147147147147147147147147147147147	USOCR	
21	7	("5397917"   "6075710"   "6150724"   "6252301"	USPAT	2004/08/19 10:25
00		"6287890"   "6339254"   "6521485").PN.		
22	9	174/52.2.ccls. and (flexible and overmold\$3)	USPAT;	2004/08/19 10:27
]			EPO; JPO;	
			DERWENT;	
			USOCR	

,,,,				
23	7	174/254.ccls. and (flexible and overmold\$3)	USPAT; EPO; JPO;	2004/08/19 10:27
			DERWENT;	
			USOCR	
24	13	174/260-263.ccls. and (flexible and overmold\$3)	USPAT;	2004/08/19 10:28
24	'3	174/200-203.ccis. and (flexible and overmology)		2004/06/19 10:28
			EPO; JPO;	
			DERWENT;	
25	12	264/760 764 pale, and (flexible and example 42)	USOCR	0004/00/40 40 00
25	12	361/760-764.ccls. and (flexible and overmold\$3)	USPAT;	2004/08/19 10:29
			EPO; JPO;	
			DERWENT;	
00	_	400/400	USOCR	
26	5	438/123.ccls. and (flexible and overmold\$3)	USPAT;	2004/08/19 10:29
			EPO; JPO;	
			DERWENT;	
			USOCR	
27	3225	BGA adj package	USPAT;	2004/08/19 10:29
			EPO; JPO;	
			DERWENT;	
			USOCR	
28	13594	(flexible same (board or substrate)) and fold\$3	USPAT;	2004/08/19 10:30
			EPO; JPO;	
			DERWENT;	
			USOCR	
29	10	(BGA adj package) and ((flexible same (board or	USPAT;	2004/08/19 10:32
		substrate)) and fold\$3)	EPO; JPO;	
		,, ,,	DERWENT;	
			USOCR	
30	3029	printed adj circuit adj substrate	USPAT;	2004/08/19 10:32
		•	EPO; JPO;	
			DERWENT;	İ
			USOCR	
31	124	(printed adj circuit adj substrate) and fold\$3	USPAT;	2004/08/19 10:32
		(, , , , , , , , , , , , , , , , , , ,	EPO; JPO;	200 1100110 10.02
			DERWENT;	
			USOCR	
32	15	((printed adj circuit adj substrate) and fold\$3) and	USPAT;	2004/08/19 10:34
		(encapsulat\$3 or overmoid\$3)	EPO; JPO;	2004/00/15 10:04
		(charponius)	DERWENT;	ľ
			USOCR	}
33	0	plastic adj overnolding	USPAT;	2004/08/19 10:34
		placae aaj ovornolanig	EPO; JPO;	2004/06/19 10.34
			DERWENT;	
			USOCR	
34	47	plastic adj overmolding	USPAT;	2004/08/19 10:34
		Piacas and over informing	EPO; JPO;	2004/00/19 10:34
			DERWENT;	ĺ
35	12	(plastic adj overmolding) and (board or substrate)	USOCR	2004/09/40 40 24
	12	(poard or substrate)	USPAT;	2004/08/19 10:34
			EPO; JPO;	]
			DERWENT;	
L		<u> </u>	USOCR	1